

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EX 2
9/11/02
#3/a

In re application of :
Yuuichiro KAJIWARA et al. : **Attn: APPLICATION BRANCH**
Serial No. NEW : **Docket No. 2001_1763A**
Filed November 28, 2001 ✓ :

A LATEX FOR DIP MOLDING AND A DIP
MOLDED PRODUCT

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to calculating the filing fee, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend the claims as follows:

A1
4. (Amended) The latex for dip molding according to claim 1, wherein the emulsion polymerization is conducted by the use of redox type of polymerization initiator containing no transition metal salt.

A2
8. (Amended) The latex for dip molding according to claim 1, wherein 100 parts by weight of the monomer mixture comprises 15 to 45 parts by weight of a vinyl cyanide monomer, 35 to 80 parts by weight of a conjugated diene monomer, 0.1 to 20 parts by weight of an ethylenically unsaturated carboxylic acid, and 0 to 20 parts by weight of other ethylenically unsaturated monomer copolymerizable with the above monomers.

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